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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/904,663	07/16/2001	Mikio Ohtaki	KAN 120D1	7934	
23995 75	590 04/17/2002				
RABIN & CHAMPAGNE, PC 1101 14TH STREET, NW SUITE 500			EXAMINER		
			HOLLINGTON, JERMELE M		
WASHINGTON, DC 20005			ART UNIT	PAPER NUMBER	
			2829	2829	
			DATE MAILED: 04/17/2002	DATE MAILED: 04/17/2002	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)
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Office Action Summary		09/904,663	OHTAKI, MIKIO
	omec Action Cummary	Examiner	Art Unit
	The MAILING DATE of this communication and	Jermele M. Hollington	2829
Period fo	The MAILING DATE of this communication app or Reply	ears on the cover sheet with the d	correspondence address
THE - Exte after - If the - If NC - Failu - Any	ORTENED STATUTORY PERIOD FOR REPLY MAILING DATE OF THIS COMMUNICATION. Insions of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication. It is period for reply specified above is less than thirty (30) days, a reply of period for reply is specified above, the maximum statutory period were to reply within the set or extended period for reply will, by statute, reply received by the Office later than three months after the mailing end patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be time within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. & 133).
1)[	Responsive to communication(s) filed on July	16, 2001	
2a)□		is action is non-final.	
3)	Since this application is in condition for allowa		rosecution as to the merits is
,	closed in accordance with the practice under		
•	ion of Claims		
	Claim(s) <u>21-41</u> is/are pending in the applicatio		
	4a) Of the above claim(s) is/are withdray	vn from consideration.	
5)	Claim(s) is/are allowed.		
6)⊠	Claim(s) <u>21-41</u> is/are rejected.		
7)	Claim(s) is/are objected to.		
	Claim(s) are subject to restriction and/or	election requirement.	
• -	ion Papers		
	The specification is objected to by the Examiner		
10)🗹	The drawing(s) filed on <u>01 October 2001</u> is/are:	a) ☐ accepted or b) ☒ objected to b	by the Examiner.
	Applicant may not request that any objection to the		· ·
11)[	The proposed drawing correction filed on		ved by the Examiner.
_	If approved, corrected drawings are required in rep	·	
12)[]	The oath or declaration is objected to by the Exa	aminer.	
Priority u	ınder 35 U.S.C. §§ 119 and 120		
13)ဩ	Acknowledgment is made of a claim for foreign	priority under 35 U.S.C. § 119(a)	)-(d) or (f).
a)[	☑ All b) ☐ Some * c) ☐ None of:		
	1. Certified copies of the priority documents	s have been received.	
	$2. \boxtimes$ Certified copies of the priority documents	s have been received in Application	on No. <u>09/434,490</u> .
* 5	3. Copies of the certified copies of the priori application from the International Bur see the attached detailed Office action for a list of	eau (PCT Rule 17.2(a)).	•
<u></u>	acknowledgment is made of a claim for domestic	·	
,	) $\square$ The translation of the foreign language pro-		, , , , , , , , , , , , , , , , , , , ,
	Acknowledgment is made of a claim for domestic		
Attachmen			
1) 🔀 Notice 2) 🔲 Notice	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of Informal P	(PTO-413) Paper No(s)
Patent and Tr	ademark Office		

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#### **DETAILED ACTION**

#### Priority

Acknowledgment is made of applicant's claim for foreign priority under 35
 U.S.C. 119(a)-(d). The certified copy has been filed in parent Application No. 09/434490, filed on Nov. 5, 1999.

#### **Drawings**

- 2. Figures 29-33 should be designated by a legend such as --Prior Art-- because only that which is old is illustrated. See MPEP § 608.02(g). A proposed drawing correction or corrected drawings are required in reply to the Office action to avoid abandonment of the application. The objection to the drawings will not be held in abeyance.
- 3. The drawings are objected to under 37 CFR 1.83(a). The drawings must show every feature of the invention specified in the claims. Therefore, plurality of electrodes are ball-type [claims 27, 34 and 41] must be shown or the feature(s) canceled from the claim(s). No new matter should be entered.

A proposed drawing correction or corrected drawings are required in reply to the Office action to avoid abandonment of the application. The objection to the drawings will not be held in abeyance.

### Claim Objections

4. Claim 28 is objected to because of the following informalities: it is not clear if "a resist film" is the same as "the resin film." If there are the same, the examiner will like to suggest to change one or the other to have a consistent terminology in the claim. If there are not the same.

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then the limitation "the resin film" in line 8 is insufficient antecedent basis in the claim.

Appropriate correction is required.

5. Applicant is advised that should claim 28 be found allowable, claim 35 will be objected to under 37 CFR 1.75 as being a substantial duplicate thereof. When two claims in an application are duplicates or else are so close in content that they both cover the same thing. despite a slight difference in wording, it is proper after allowing one claim to object to the other as being a substantial duplicate of the allowed claim. See MPEP § 706.03(k).

## Claim Rejections - 35 USC § 112

- 6. The following is a quotation of the second paragraph of 35 U.S.C. 112:

  The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter, which the applicant regards as his invention.
- 7. Claims 21-41 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Regarding claims 21-22, 28-29 and 35-36, it is not clear what is "dividing the wafer into a plurality of semiconductor devices." On page 24, lines 3-4 and page 27 lines 7-8, it states: "The wafer to be measured ... is resin-coated and is ultimately divided into a plurality of CSP devices ..."

For examination purpose, the examiner assumes that any item for wafer cutting could be use to divide the wafer into semiconductor devices.

Regarding claims 27, 34 and 41, it is not clear how "the plurality of electrodes are ball-type." Since these claims depend off of independent claims, it appears the electrodes located on the wafer are ball-type. However, for example page 11 lines 16-32, it describes the electrodes

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(105b) in the film (105) is the ball-type rather than the electrode (201a) on the wafer (201) to be tested.

For examination purpose, the examiner is assuming the plurality of the electrodes in the film are ball-type rather than the electrodes on the wafer.

## Claim Rejections - 35 USC § 102

8. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in-
- (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effect under this subsection of a national application published under section 122(b) only if the international application designating the United States was published under Article 21(2)(a) of such treaty in the English language; or
- (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that a patent shall not be deemed filed in the United States for the purposes of this subsection based on the filing of an international application filed under the treaty defined in section 351(a).
- 9. Claims 21-41 are rejected under 35 U.S.C. 102(e) as being anticipated by Nakata et al (6297658).

Regarding claims 21, 28 and 35, Nakata et al discloses [see fig. 1] a method of manufacturing probe card of a wafer burn-in cassette comprising providing a semiconductor wafer (10) having a plurality of circuit elements [not shown] on a surface [not number but shown in fig. 1] thereof [see column 3 lines 27-30 and column 6 lines 25-26], forming on the wafer surface [not number but shown] a plurality of electrodes (16) connected with the circuit elements [see column 6 lines 30-31], coating the wafer surface with a resin film (represented as probe card 12) [see column 6 lines 27-28], the plurality of electrodes (16)being exposed through the resin film (12) [see fig. 1], inserting the wafer (10) into a burn-in apparatus (represented as burn-in

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cassette), inherently testing the plurality of circuit elements [not shown] for electrical functions in the bur-in apparatus (burn-in cassette) through the plurality of electrodes (16) and inherently dividing the wafer (10) [see fig. 3 with scribe lines dividing each semiconductor device] into the plurality of semiconductor device [not number but shown in fig. 3].

Regarding claims 22, 29 and 36, Nakata inherently discloses dividing the wafer after testing [see fig. 3].

Regarding claims 23, 25, 30, 32, 37 and 39, Nakata discloses mounting the wafer (10) on a circuit board (represented as wiring board 13) with an elastic sheet or film (represented as conductive rubber 21) interposed there between including electrically connecting wiring circuit [nit number but shown in fig. 1] on the circuit board (13) to the electrodes (16) on the wafer (10) through bump electrode (17) in the film (21).

Regarding claims 24, 26, 31, 33, 38 and 40, Nakata discloses disposing over the wafer (10) a holding plate (represented as first sealed member 15 and second sealed member 25) having a through hole (26) and pressing the wafer (10) on the circuit board (13) with the holding plate (15 and 25) [see column 6 line 56- column 7 line 54].

Regarding claims 27, 34 and 41, Nakata discloses the plurality of electrodes (17) are ball-type [see fig. 1].

#### Conclusion

10. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Yoshizawa et al (5606263), Hamaguchi et al (5821762), Budnatis t al (5896038),

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Nakata et al (5945834), Jitsumori et al (6232791) and Khoury et al (6250933) disclose a method and apparatus for testing a wafer using bump electrodes on bump pads.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jermele M. Hollington whose telephone number is (703) 305-1653. The examiner can normally be reached on M-F (9:00-3:30 EST) First Friday Off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Michael Sherry can be reached on (703) 308-1680. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 308-7722 for regular communications and (703) 308-7382 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-1782.

GROUP 2829

Jermele M. Hollington

Examiner Art Unit 2829

April 11, 2002